

Application Serial No. 10/812,639
Reply to Office Action of November 28, 2007

PATENT
Docket: CU-3673

REMARKS

In the Office Action, dated November 28, 2007, the Examiner states that Claims 1-8 are pending, and Claims 1-8 are rejected. By the present Amendment, Applicant amend the claims.

In the Office Action, Claims 1, 2, 4-6 and 8 are rejected under 35 U.S.C. §102(b) as being anticipated by Segawa et al. (US 2002/0057468). Claims 3 and 7 are rejected under 35 U.S.C. §103(a) as being unpatentable over Segawa et al. in view of Akimoto et al. (US 2002/0191103). The Applicant considers that the amendments to the claims overcome these rejections.

Each of the independent claims have been amended to clarify that the contacting end is structured to contact a side of the module/electrode pad. This side/lateral contact imposes a lateral force on the module/electrode pad. The prior art does not disclose this feature.

In contrast, Segawa discloses contacting members 236 that contact the underside of a module (Figures 5, 12B, 13B and 13C) or contacting members/engagement members 244 that contact an upper surface of a module (Figures 12A, 13B, and 13C). There is no disclosure of contact on a side surface of the module/electrode pad that imposes a lateral force.

Akimoto does not disclose any corresponding contact member.

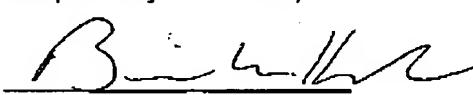
Therefore, the Applicant considers that the amended claims are neither anticipated by or obvious in view of the relied upon cited prior art references.

In light of the foregoing response, all the outstanding objections and rejections are considered overcome. Applicant respectfully submits that this application should now be in condition for allowance and respectfully requests favorable consideration.

Respectfully submitted,

March 19, 2008

Date


Attorney for Applicant
Brian W. Hameder
c/o Ladas & Parry LLP
224 South Michigan Avenue
Chicago, Illinois 60604
(312) 427-1300
Reg. No. 45613